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(19) **United States**(12) **Patent Application Publication****Lohan et al.**(10) **Pub. No.: US 2022/0361353 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **LOW PROFILE POWER MODULE PACKAGE****H01L 23/532** (2006.01)**H01L 23/538** (2006.01)(71) Applicant: **Toyota Motor Engineering & Manufacturing North America, Inc.,**
Plano, TX (US)(52) **U.S. Cl.**CPC **H05K 5/0286** (2013.01); **H02M 7/537**
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H01L 23/5385 (2013.01)(72) Inventors: **Danny Lohan**, Northville, MI (US);
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Methods, systems, and apparatus for a module electronics package. The modular electronics package includes a main circuit. The first main circuit board is configured to provide electrical interconnections to form an electric circuit. The modular electronics package includes a first power module. The first power module includes a first power device card and a first expansion slot. The first power device card is configured to be inserted into the first expansion slot and to be electrically coupled to the main circuit board via the first expansion slot.

